

REVISIONS

[查询"5962-9167601KXA"供应商](#)

LTR	DESCRIPTION	DATE (YR-MO-DA)	APPROVED
C	Added a class K device. Redrew entire document. -sld	98-04-09	K. A. Cottongim

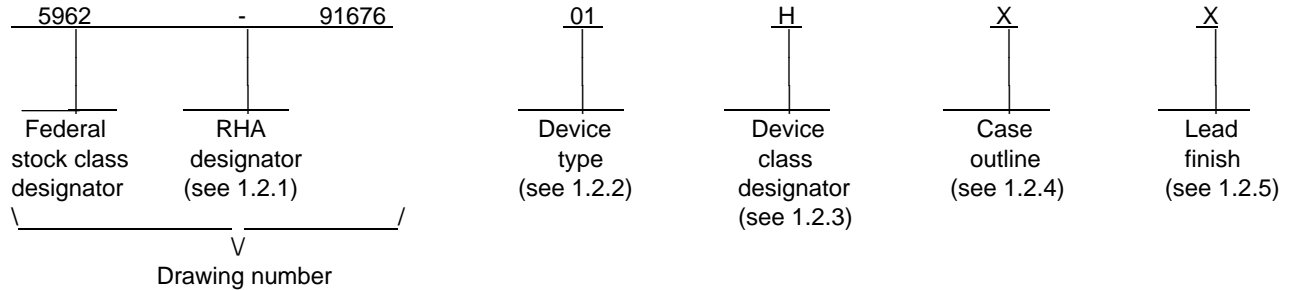
REV																				
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REV STATUS	REV	C	C	C	C	C	C	C	C	C	C	C	C	C	C	C	C	C	C	
OF SHEETS	SHEET	1	2	3	4	5	6	7	8	9	10	11	12	13						
PMIC N/A	PREPARED BY Steve Duncan	<b>DEFENSE SUPPLY CENTER COLUMBUS</b>  <b>COLUMBUS, OHIO 43216</b>																		
<b>STANDARD MICROCIRCUIT DRAWING</b>	CHECKED BY Michael C. Jones																			
THIS DRAWING IS AVAILABLE FOR USE BY ALL DEPARTMENTS AND AGENCIES OF THE DEPARTMENT OF DEFENSE	APPROVED BY Gregory Lude	<b>MICROCIRCUIT, DIGITAL, OPTICAL COUPLED FILTER, HYBRID,</b>																		
	DRAWING APPROVAL DATE 92-07-07																			
	REVISION LEVEL C																			SIZE A
AMSC N/A	SHEET		1 OF 13																	

1. SCOPE

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1.1 Scope. This drawing documents five product assurance classes, class D (lowest reliability), class E, (exceptions), class G (lowest high reliability), class H (high reliability), and class K, (highest reliability) and a choice of case outlines and lead finishes are available and are reflected in the Part or Identifying Number (PIN). When available, a choice of radiation hardness assurance levels are reflected in the PIN.

1.2 PIN. The PIN shall be as shown in the following example:



1.2.1 Radiation hardness assurance (RHA) designator. Device classes H and K RHA marked devices shall meet the MIL-PRF-38534 specified RHA levels and shall be marked with the appropriate RHA designator. A dash (-) indicates a non-RHA device.

1.2.2 Device type(s). The device type(s) identify the circuit function as follows:

<u>Device type</u>	<u>Generic number</u>	<u>Circuit function</u>
01	66079, 66079-300	Single channel, optocoupler

1.2.3 Device class designator. This device class designator shall be a single letter identifying the product assurance level as follows:

<u>Device class</u>	<u>Device performance documentation</u>
D, E, G, H, or K	Certification and qualification to MIL-PRF-38534

1.2.4 Case outline(s). The case outline(s) are as designated in MIL-STD-1835 and as follows:

<u>Outline letter</u>	<u>Descriptive designator</u>	<u>Terminals</u>	<u>Package style</u>
X	See figure 1	7	Co-axial
Y	See figure 1	7	Bolthead co-axial

1.2.5 Lead finish. The lead finish shall be as specified in MIL-PRF-38534.

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1.3 Absolute maximum ratings. 1/

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Supply voltage range (V <sub>CC</sub> ) .....	+7.0 V dc (1 minute maximum)
Input current .....	20 mA
Storage temperature range .....	-65° C to +150° C
Power dissipation (T <sub>C</sub> = +125° C).....	175 mW
Lead temperature (soldering, 10 seconds).....	+260° C
Junction temperature (T <sub>J</sub> ).....	+175° C

1.4 Recommended operating conditions.

Supply voltage range (V <sub>CC</sub> ) .....	+4.5 V dc to +5.5 V dc
High level input current.....	12.5 mA minimum <u>2/</u>
Low level input current .....	250 μA dc maximum
Normalized fanout (TTL load).....	6 maximum
Case operating temperature range (T <sub>C</sub> ).....	-55° C to +125° C

2. APPLICABLE DOCUMENTS

2.1 Government specification, standards, and handbook. The following specification, standards, and handbook form a part of this drawing to the extent specified herein. Unless otherwise specified, the issues of these documents are those listed in the issue of the Department of Defense Index of Specifications and Standards (DoDISS) and supplement thereto, cited in the solicitation.

SPECIFICATION

DEPARTMENT OF DEFENSE

MIL-PRF-38534 - Hybrid Microcircuits, General Specification for.

STANDARDS

DEPARTMENT OF DEFENSE

- MIL-STD-883 - Test Methods and Procedures for Microelectronics.
- MIL-STD-973 - Configuration Management.
- MIL-STD-1835 - Microcircuit Case Outlines.

HANDBOOK

DEPARTMENT OF DEFENSE

MIL-HDBK-780 - Standard Microcircuit Drawings.

(Unless otherwise indicated, copies of the specification, standards, and handbook are available from the Standardization Document Order Desk, 700 Robbins Avenue, Building 4D, Philadelphia, PA 19111-5094.)

2.2 Order of precedence. In the event of a conflict between the text of this drawing and the references cited herein, the text of this drawing takes precedence. Nothing in this document, however, supersedes applicable laws and regulations unless a specific exemption has been obtained.

- 
- 1/ Stresses above the absolute maximum rating may cause permanent damage to the device. Extended operation at the maximum levels may degrade performance and affect reliability.
  - 2/ This condition permits at least 20 percent h<sub>F</sub> (CTR) degradation. This initial switching threshold is 10 mA dc or less.

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3. REQUIREMENTS

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3.1 Item requirements. The individual item performance requirements for device classes D, E, G, H, and K shall be in accordance with MIL-PRF-38534. Compliance with MIL-PRF-38534 may include the performance of all tests herein or as designated in the device manufacturer's Quality Management (QM) plan or as designated for the applicable device class. Therefore, the tests and inspections herein may not be performed for the applicable device class (see MIL-PRF-38534). Furthermore, the manufacturers may take exceptions or use alternate methods to the tests and inspections herein and not perform them. However, the performance requirements as defined in MIL-PRF-38534 shall be met for the applicable device class.

3.2 Design, construction, and physical dimensions. The design, construction, and physical dimensions shall be as specified in MIL-PRF-38534 and herein.

3.2.1 Case outline(s). The case outline(s) shall be in accordance with 1.2.4 herein and figure 1.

3.2.2 Terminal connections. The terminal connections shall be as specified on figure 2.

3.2.3 Switching test circuit and waveforms. The switching test circuit and waveforms shall be as specified on figure 3.

3.3 Electrical performance characteristics. Unless otherwise specified herein, the electrical performance characteristics are as specified in table I and shall apply over the full specified operating temperature range.

3.4 Electrical test requirements. The electrical test requirements shall be the subgroups specified in table II. The electrical tests for each subgroup are defined in table I.

3.5 Marking of Device(s). Marking of device(s) shall be in accordance with MIL-PRF-38534. The device shall be marked with the PIN listed in 1.2 herein. In addition, the manufacturer's vendor similar PIN may also be marked as listed in QML-38534.

3.6 Data. In addition to the general performance requirements of MIL-PRF-38534, the manufacturer of the device described herein shall maintain the electrical test data (variables format) from the initial quality conformance inspection group A lot sample, for each device type listed herein. Also, the data should include a summary of all parameters manually tested, and for those which, if any, are guaranteed. This data shall be maintained under document revision level control by the manufacturer and be made available to the preparing activity (DSCC-VA) upon request.

3.7 Certificate of compliance. A certificate of compliance shall be required from a manufacturer in order to supply to this drawing. The certificate of compliance (original copy) submitted to DSCC-VA shall affirm that the manufacturer's product meets the performance requirements of MIL-PRF-38534 and herein.

3.8 Certificate of conformance. A certificate of conformance as required in MIL-PRF-38534 shall be provided with each lot of microcircuits delivered to this drawing.

4. QUALITY ASSURANCE PROVISIONS

4.1 Sampling and inspection. Sampling and inspection procedures shall be in accordance with MIL-PRF-38534 or as modified in the device manufacturer's Quality Management (QM) plan. The modification in the QM plan shall not affect the form, fit, or function as described herein.

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TABLE I. Electrical performance characteristics.

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Test	Symbol	Conditions -55°C ≤ T <sub>C</sub> ≤ +125°C 4.5 V dc ≤ V <sub>CC</sub> ≤ 5.5 V dc unless otherwise specified	Group A subgroups	Device type	Limits		Unit
					Min	Max	
Low level output voltage	V <sub>OL</sub>	V <sub>CC</sub> = 5.5 V, I <sub>F</sub> = 10 mA, I <sub>OL</sub> = 10 mA 1/	1,2,3	01		0.6	V
High level output current	I <sub>OH</sub>	V <sub>CC</sub> = 5.5 V, V <sub>O</sub> = 5.5 V, I <sub>F</sub> = 250 mA	1,2,3	01		250	μA
High level supply current	I <sub>CCH</sub>	V <sub>CC</sub> = 5.5 V, I <sub>F</sub> = 0 mA	1,2,3	01		20	mA
Low level supply current	I <sub>CCL</sub>	V <sub>CC</sub> = 5.5 V, I <sub>F</sub> = 20 mA	1,2,3	01		30	mA
Input forward voltage	V <sub>F</sub>	I <sub>F</sub> = 20 mA	1,2	01		1.75	V
			3			1.85	
Input reverse breakdown voltage	V <sub>BR</sub>	I <sub>R</sub> = 10 μA	1,2,3	01	5		V
Input to output insulation leakage current 2/	I <sub>IO</sub>	V <sub>IO</sub> = 1000 V dc, t = 5 sec, relative humidity = 45%, T <sub>C</sub> = +25°C	1	01		1.0	μA
Input to output capacitance 3/ 6/	C <sub>IO</sub>	f = 1 MHz, T <sub>C</sub> = +25°C	1	01		3.0	pF
Input to case isolation leakage current	I <sub>IC</sub>	V <sub>IC</sub> = 500 V, pins 1 and 2 shorted together, T <sub>C</sub> = +25°C	1	01		1.0	μA
Output to case isolation leakage current	I <sub>OC</sub>	V <sub>OC</sub> = 500 V, pins 4, 5, and 6 are shorted together, T <sub>C</sub> = +25°C	1	01		1.0	μA
Input to case capacitance	C <sub>IC</sub>	f = 1 MHz, T <sub>C</sub> = +25°C	4	01		5.0	pf

See footnotes at end of table.

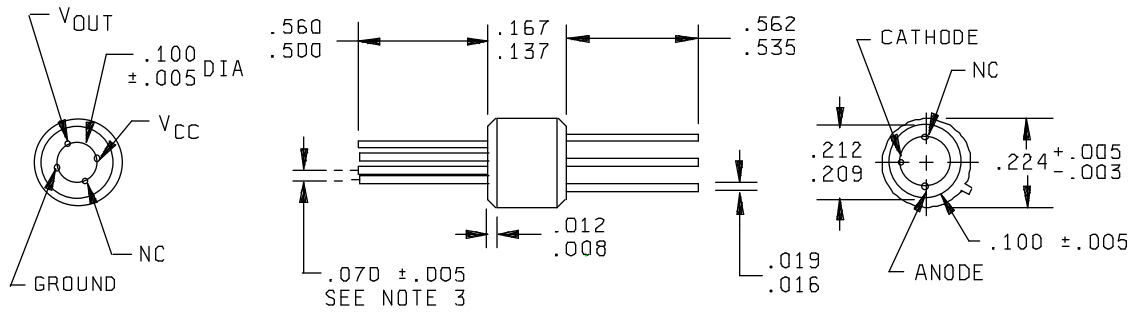
<b>STANDARD MICROCIRCUIT DRAWING</b>  DEFENSE SUPPLY CENTER COLUMBUS COLUMBUS, OHIO 43216-5000	SIZE <b>A</b>		<b>5962-91676</b>
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TABLE I. Electrical performance characteristics - Continued  
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Test	Symbol	Conditions -55°C ≤ T <sub>C</sub> ≤ +125°C 4.5 V dc ≤ V <sub>CC</sub> ≤ 5.5 V dc unless otherwise specified	Group A subgroups	Device type	Limits		Unit
					Min	Max	
Propagation delay time, <u>4/</u> low to high output level	t <sub>PLH</sub>	R <sub>1</sub> = 510Ω, C <sub>L</sub> = 15 pf, I <sub>F</sub> = 13 mA	9	01		100	ns
			10,11			140	
Propagation delay time, <u>5/</u> high to low output level	t <sub>PHL</sub>	R <sub>1</sub> = 510Ω, C <sub>L</sub> = 15 pf, I <sub>F</sub> = 13 mA	9	01		100	ns
			10,11			140	
Common mode transient immunity at output high level <u>6/</u>	CM <sub>H</sub>	V <sub>CM</sub> - 10 Vp-p, I <sub>F</sub> = 0 mA, V <sub>O</sub> = 2 V min, R <sub>L</sub> = 510Ω	9,10,11	01	1000		V/μs
Common mode transient immunity at output low level <u>6/</u>	CM <sub>L</sub>	V <sub>CM</sub> - 10 Vp-p, I <sub>F</sub> = 10 mA, V <sub>O</sub> = 0.8 V max, R <sub>L</sub> = 510Ω	9,10,11	01	1000		V/μs

- 1/ It is essential that a ceramic bypass capacitor of .01 μf be connected from V<sub>CC</sub> to ground.  
2/ Device considered a two-terminal device, pins 1 through 3 are shorted together and pins 4 through 7 are shorted together.  
3/ Measured between each input pair shorted together and all outputs shorted together.  
4/ The t<sub>PLH</sub> propagation delay is measured from the 6.5 mA point on the trailing edge of the input pulse to the 1.5 V point on the trailing edge of the output pulse.  
5/ The t<sub>PHL</sub> propagation delay is measured from the 6.5 mA point on the leading edge of the input pulse to the 1.5 V point on the leading edge of the output pulse.  
6/ Parameters shall be tested as part of device initial characterization and after design and process changes. Parameters shall be guaranteed to the limits specified in table I for all lots not specifically tested.

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Inches	mm
.005	.127
.008	.203
.012	.305
.016	.406
.019	.483
.070	1.778
.100	2.540
.137	3.480
.167	4.242
.209	5.308
.212	5.384
.500	12.700
.535	13.590
.560	14.224
.562	14.275

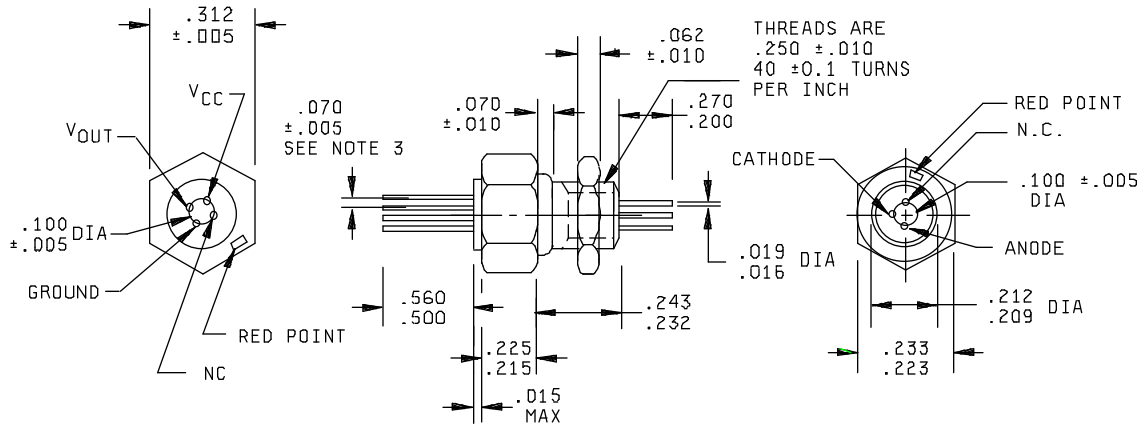
NOTES:

1. Dimensions are in inches:
2. Metric equivalents are for general information only.
3. Measured at base of the header.

FIGURE 1. Case outline.

<b>STANDARD MICROCIRCUIT DRAWING</b>  DEFENSE SUPPLY CENTER COLUMBUS COLUMBUS, OHIO 43216-5000	SIZE <b>A</b>		<b>5962-91676</b>
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CASE Y



Inches	mm
.005	.127
.010	.254
.015	.381
.016	.406
.019	.483
.062	1.575
.070	1.778
.100	2.540
.200	5.080
.209	5.309
.212	5.385
.215	5.461
.223	5.664
.225	5.715
.232	5.893
.233	5.918
.243	6.172
.250	6.350
.270	6.858
.312	7.925
.500	12.700
.560	14.224

NOTES:

1. Dimensions are in inches:
2. Metric equivalents are for general information only.
3. Measured at base of the header.

FIGURE 1. Case outline - Continued.

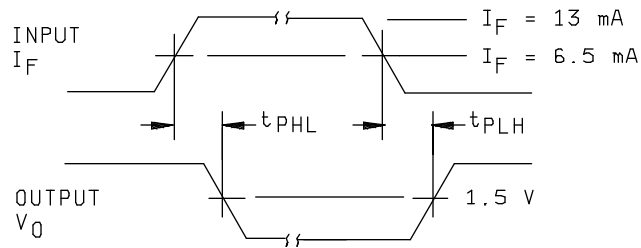
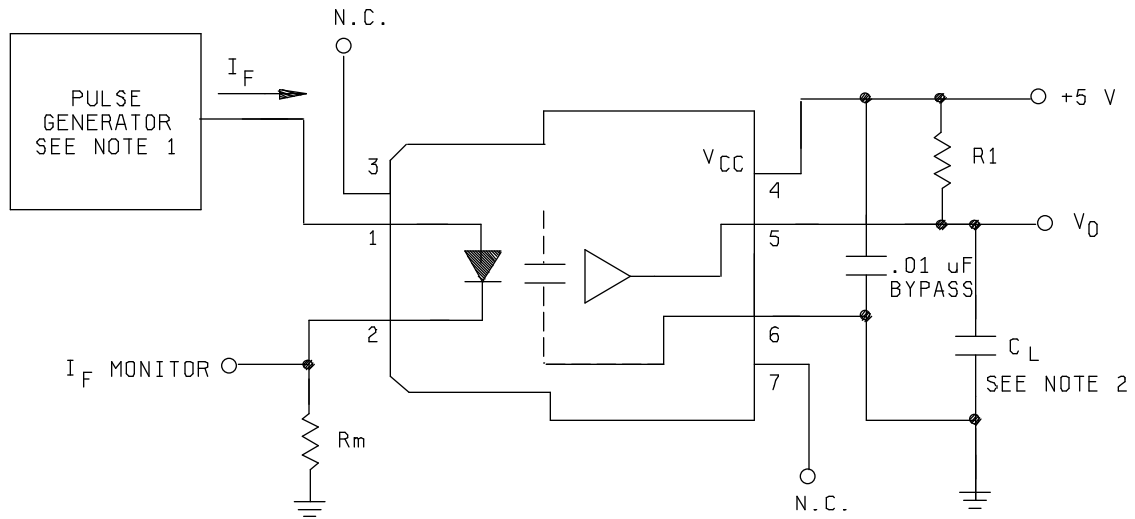
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Device type	01
Case outlines	X and Y
Terminal numbers	Terminal connections
1	Anode
2	Cathode
3	No connection
4	Vcc
5	Vout
6	Ground
7	No connection

FIGURE 2. Terminal connections.

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NOTES:

1. All input pulses supplied by generators having the following characteristics:  $Z_o = 50\Omega$ ,  $t_r = 5\text{ ns}$ .
2.  $C_L$  includes probe and stray wiring capacitance.

FIGURE 3. Switching test circuit and waveforms.

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TABLE II. Electrical test requirements.

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MIL-PRF-38534 test requirements	Subgroups (in accordance with MIL-PRF-38534, group A test table)
Interim electrical parameters	1
Final electrical parameters	1*,2,3,4,9,10,11
Group A test requirements	1,2,3,4,9,10,11
Group C end-point electrical parameters	1,2,3
MIL-STD-883, group E end-point electrical parameters for RHA devices	Subgroups** (in accordance with method 5005, group A test table)

\* PDA applies to subgroup 1.

\*\* When applicable to this standard microcircuit drawing,  
the subgroups shall be defined.

4.2 Screening. Screening shall be in accordance with MIL-PRF-38534. The following additional criteria shall apply:

a. Burn-in test, method 1015 of MIL-STD-883.

(1) Test condition A, B, C, or D. The test circuit shall be maintained by the manufacturer under document revision level control and shall be made available to either DSCC-VA or the acquiring activity upon request. Also, the test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in test method 1015 of MIL-STD-883.

(2)  $T_A$  as specified in accordance with table I of method 1015 of MIL-STD-883.

b. Interim and final electrical test parameters shall be as specified in table II herein, except interim electrical parameter tests prior to burn-in are optional at the discretion of the manufacturer.

4.3 Conformance and periodic inspections. Conformance inspection (CI) and periodic inspection (PI) shall be in accordance with MIL-PRF-38534 and as specified herein.

4.3.1 Group A inspection (CI). Group A inspection shall be in accordance with MIL-PRF-38534 and as follows:

a. Tests shall be as specified in table II herein.

b. Subgroups 5, 6, 7, and 8 shall be omitted.

4.3.2 Group B inspection (PI). Group B inspection shall be in accordance with MIL-PRF-38534.

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4.3.3 Group C inspection (PI). Group C inspection shall be in accordance with MIL-PRF-38534 and as follows:

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- a. End-point electrical parameters shall be as specified in table II herein.
- b. Steady-state life test, method 1005 of MIL-STD-883.
  - (1) Test condition A, B, C, or D. The test circuit shall be maintained by the manufacturer under document revision level control and shall be made available to either DSCC-VA or the acquiring activity upon request. Also, the test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in test method 1005 of MIL-STD-883.
  - (2)  $T_A$  as specified in accordance with table I of method 1005 of MIL-STD-883.
  - (3) Test duration: 1,000 hours, except as permitted by method 1005 of MIL-STD-883.

4.3.4 Group D inspection (PI). Group D inspection shall be in accordance with MIL-PRF-38534.

4.3.5 Group E inspection. Group E inspection is required only for parts intended to be marked as radiation hardness assured (see 3.5 herein). RHA levels shall be M, D, R, and H. RHA quality conformance inspection sample tests shall be performed at the RHA level specified in the acquisition document.

- a. RHA tests for levels M, D, R, and H shall be performed through each level to determine at what levels the devices meet the RHA requirements. These RHA tests shall be performed for initial qualification and after design or process changes which may affect the RHA performance of the device.
- b. End-point electrical parameters shall be as specified in table II herein.
- c. Prior to total dose irradiation, each selected sample shall be assembled in its qualified package. It shall pass the specified group A electrical parameters in table I for subgroups specified in table II herein.
- d. The devices shall be subjected to radiation hardness assured tests as specified in MIL-PRF-38534 for RHA level being tested, and meet the postirradiation end-point electrical parameter limits as defined in table I at  $T_A = +25^\circ\text{C} \pm 5$  percent, after exposure.
- e. Prior to and during total dose irradiation testing, the devices shall be biased to establish a worst case condition as specified in the radiation exposure circuit.
- f. For device classes H and K, subgroups 1 and 2 in table V, method 5005 of MIL-STD-883 shall be tested as appropriate for device construction.
- g. When specified in the purchase order or contract, a copy of the RHA delta limits shall be supplied.

5. PACKAGING

5.1 Packaging requirements. The requirements for packaging shall be in accordance with MIL-PRF-38534.

6. NOTES

6.1 Intended use. Microcircuits conforming to this drawing are intended for use for Government microcircuit applications (original equipment), design applications, and logistics purposes.

6.2 Replaceability. Microcircuits covered by this drawing will replace the same generic device covered by a contractor-prepared specification or drawing.

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6.3 Configuration control of SMD's. All proposed changes to existing SMD's will be coordinated with the users of record for the product. Coordination will be accomplished in accordance with MIL-STD-973 using DD Form 1692, Engineering Change Proposal.

6.4 Record of users. Military and industrial users shall inform Defense Supply Center Columbus when a system application requires configuration control and the applicable SMD. DSCC will maintain a record of users and this list will be used for coordination and distribution of changes to the drawings. Users of drawings covering microelectronic devices (FSC 5962) should contact DSCC-VA, telephone (614) 692-7603.

6.5 Comments. Comments on this drawing should be directed to DSCC-VA, Columbus, Ohio 43216-5000, or telephone (614) 692-0512.

6.6 Sources of supply. Sources of supply are listed in QML-38534. The vendors listed in QML-38534 have submitted a certificate of compliance (see 3.7 herein) to DSCC-VA and have agreed to this drawing.

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DATE: 98-04-09

Approved sources of supply for SMD 5962-91676 are listed below for immediate acquisition information only and shall be added to QML-38534 during the next revision. QML-38534 will be revised to include the addition or deletion of sources. The vendors listed below have agreed to this drawing and a certificate of compliance has been submitted to and accepted by DSCC-VA. This bulletin is superseded by the next dated revision of QML-38534.

Standard microcircuit drawing PIN <u>1/</u>	Vendor CAGE number	Vendor similar PIN <u>2/</u>
5962-9167601HXA	31757	66079-001
5962-9167601HXC	31757	66079-001
5962-9167601HYA	31757	66079-000
5962-9167601HYC	31757	66079-000
5962-9167601KXA	31757	66079-300
5962-9167601KXC	31757	66079-300
5962-9167601KYA	31757	66079-301
5962-9167601KYC	31757	66079-301

1/ The lead finish shown for each PIN representing a hermetic package is the most readily available from the manufacturer listed for that part. If the desired lead finish is not listed contact the Vendor to determine its availability.

2/ Caution. Do not use this number for item acquisition. Items acquired to this number may not satisfy the performance requirements of this drawing.

Vendor CAGE  
number

31757

Vendor name  
and address

Micropac Industries, Incorporated  
 Optoelectronic Division  
 905 East Walnut Street  
 Garland, TX 75040-6611  
 Point of contact: Optoelectronic Division  
 725 East Walnut Street  
 Garland, TX 75040

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